B/O FORM PTO 1595 (1/31/92)  Patent and Trademark Office  RECORDATION FORM COVER SHEET  PATENTS ONLY  TSUT 0028	
1 1109	TSUT.0028
To the Honorable Commissioner of Patents and Trademarks. Pl	ease record the attached original documents or copy thereof.
1. Name of Conveying Party(ies):	2. Name and Address of Receiving Party(ies):
(1) EIICHI MURAKAMI, (2) AKIO NISHIDA, (3) KAZUNORI UMEDA, (4) KOUSUKE OKUYAMA, (5) TOSHIAKI YAMANAKA, (6) JIRO YUGAMI AND (7) SHINICHIRO KIMURA	Name: Hitachi, Ltd.  Address: 6, Kanda Surugadai 4-chome City: Chiyoda-ku, Tokyo, Japan  OCCUPATION OF COLUMN OF COL
Additional names of conveying parties attached:  Yes No  3. Nature of Conveyance:    X   Assignment	02-20-2004 102673958
<ul> <li>4. (a) Patent Application Number(s):</li> <li>If this document is being filed together with a new application, the execution date of the application is:</li> <li>Additional Numbers Attached.</li> </ul>	4. (b) Patent Numbers:
5. Name and Address of Party to whom Correspondence Concerning this Document Should be Mailed:	6. Total Number of Applications and Patents Involved: 1
Name: Stanley P. Fisher  Address: Reed Smith LLP 3110 Fairview Park Dr. Suite 1400 Falls Church, VA. 22042	7. Total Fee: \$40.00 (37 C.F.R. § 3.41)  Enclosed. Authorized to be charged to deposit account.  8. Deposit Account Number: 08-1480
	ATTACH DUPLICATE COPY OF THIS PAGE IF PAYING BY DEPOSIT ACCOUNT
DO NOT USE THIS SPACE	1
9. Statement and Signature:  To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.	

Total number of pages comprising cover sheet:

Stanley P. Fisher, Registration No. 24, 344

00000010 10775236

02 FC:8021

02/13/2004 ANABI1

40.00 OP

PATENT REEL: 014979 FRAME: 0896

## ASSIGNMENT ( 籐 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6. Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THEREOF

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside our signatures:

.....

RECORDED: 02/11/2004

INVENTOR(S) (発明者フルネームサイン)	(署名日)
1) <u>Eich: Murkami</u>	9/28/2001
2) Akio Mishida	10/5/200)
3) <u>Kazunori Uneda</u>	10/10/2001
4) Kosake Olenjama	10/5/2001
5) Toskiahi Jamanaha	
5) Jiro Yng Dmi	10/10/2001
Shinichilo (Cimura	10/10/2001
B)	
9)	
o)	

PATENT REEL: 014979 FRAME: 0897

Data Sianad